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(71) Applicant: **CASIO COMPUT CO LTD**

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(54) PLATING METHOD AND PLATING DEVICE

(57) Abstract:

PURPOSE: To make it possible to apply plating of a uniform thickness on a surface to be plated.

CONSTITUTION: An anode electrode 31 is divided to a central anode electrode 34 and first to fourth peripheral anode electrodes 35 to 38 via an insulating regions 33. A plating power source section 46 of a plating current control section 44 is a constant current source in this embodiment. The plural plating current outputs supplied therefrom are changed over to on/off by a switching circuit 45. The plating current supplied to the central anode electrode 34 is turned on for 2/3 the plating treatment time and off for 1/3 and the plating currents supplied to the first to fourth peripheral anode electrodes 35 to 38 are held tuned on at all times during the plating treatment time. The plating thickness distribution of a wafer 49 is usually

deposited thick in the central part and thin in the peripheral parts, but the bump electrodes having a uniform height are formed on the wafer 49 by controlling the energization time in the manner described above.